

ANTREX Electronics

Electronic Components Sourcing Information

Product Reference Information

Part Number: BAP51LX,315
Manufacturer: NXP USA Inc.
Package: 2-XDFN
Availability: Please confirm with sales

Product Page:

<https://antrexco.com/product/details/nxp-usa-inc/bap51lx-315.html>

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Note:

This PDF includes an ANTREX product reference cover page.

The original manufacturer datasheet follows from the next page.



BAP51LX

Silicon PIN diode

Rev. 3 — 26 November 2018

Product data sheet

1 Product profile

1.1 General description

Planar PIN diode in a SOD882D leadless ultra small plastic SMD package.

1.2 Features and benefits

- High-speed switching for RF signals
- Low diode capacitance
- Low forward resistance
- Very low series inductance
- For applications up to 3 GHz
- AEC-Q101 qualified

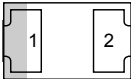
1.3 Applications

- RF attenuators and switches



2 Pinning information

Table 1. Discrete pinning

Pin	Description		Simplified outline	Symbol
1	cathode	[1]	 Transparent top view	 sym006
2	anode			

[1] The marking bar indicates the cathode.

3 Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
BAP51LX	DFN1006D-2	leadless ultra small plastic package; 2 terminals; body 1 × 0.6 × 0.4 mm	SOD882D

4 Marking code

Table 3. Marking code

Type number	Marking code ^[1]
BAP51LX	1001 0100

[1] For SOD882D binary marking code description, see [Figure 1](#).

4.1 Binary marking code description

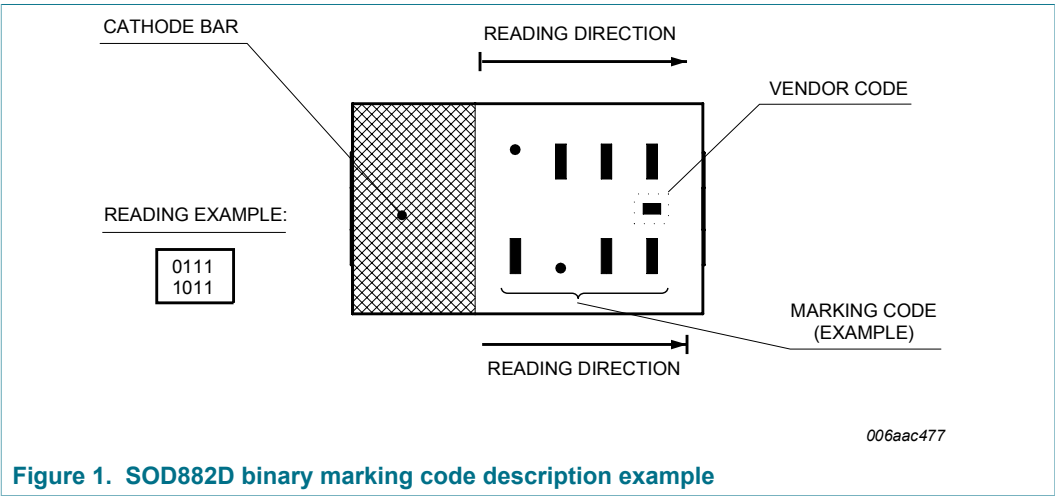


Figure 1. SOD882D binary marking code description example

5 Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	reverse voltage		-	60	V
I_F	forward current		-	100	mA
P_{tot}	total power dissipation	$T_{sp} \leq 90\text{ }^{\circ}\text{C}$	-	140	mW
T_{stg}	storage temperature		-65	+150	$^{\circ}\text{C}$
T_j	junction temperature		-65	+150	$^{\circ}\text{C}$

6 Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		66	K/W

7 Characteristics

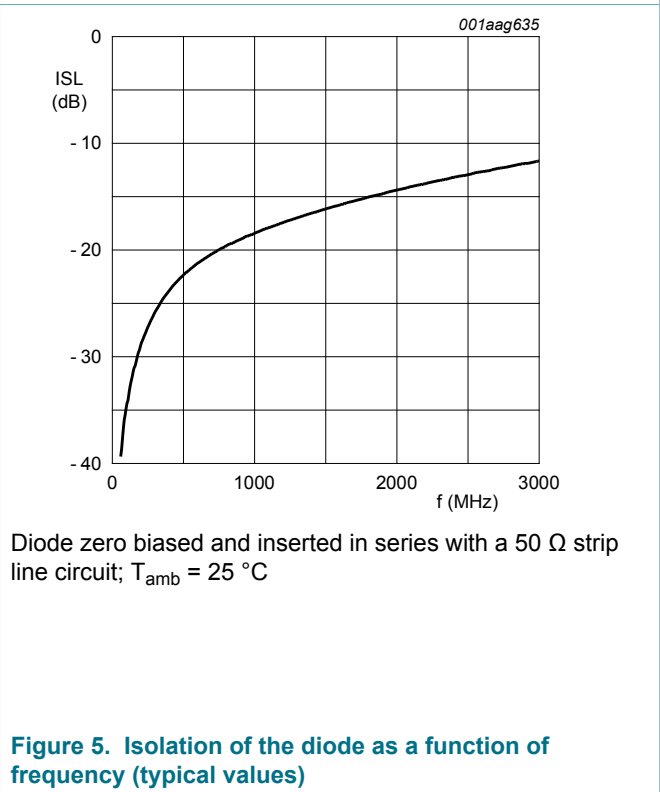
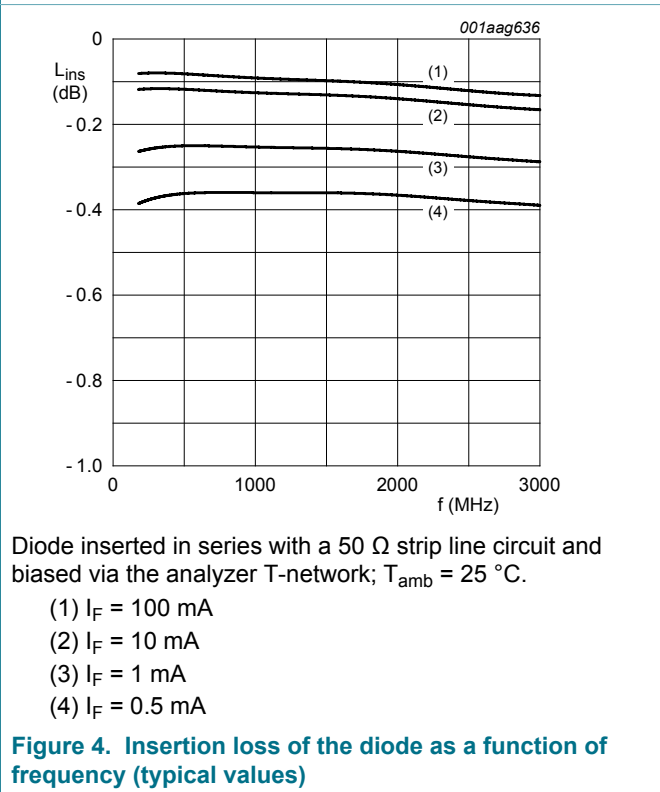
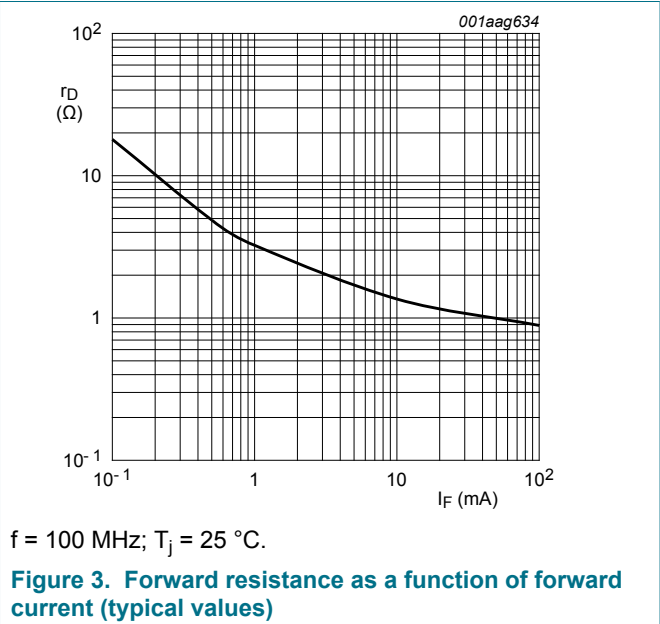
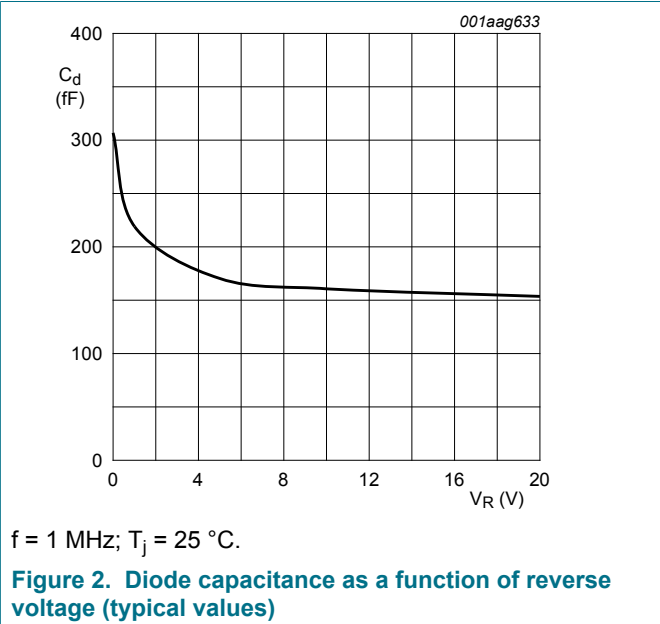
Table 6. Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified.

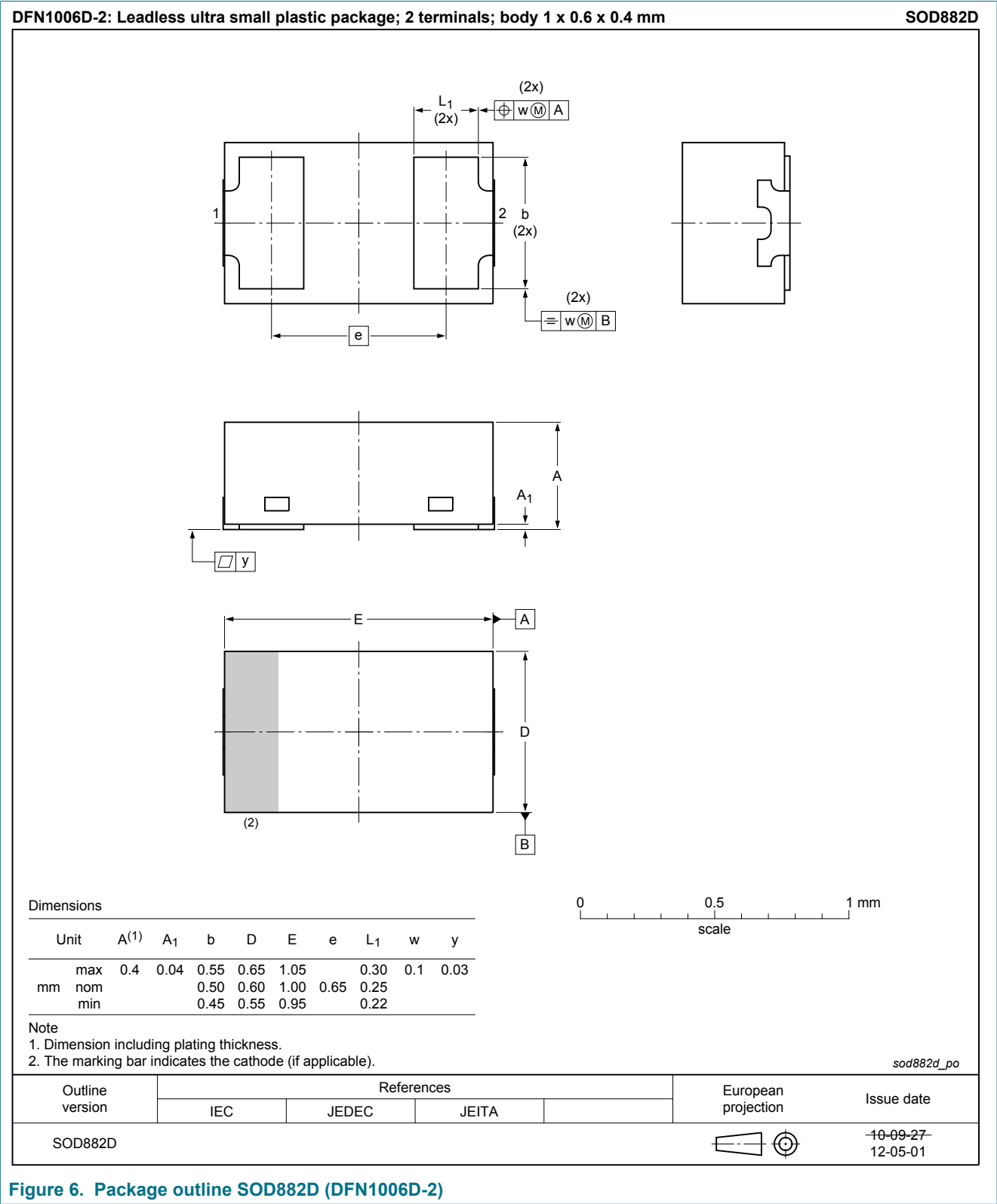
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage	$I_F = 50\text{ mA}$	-	0.95	1.1	V
I_R	reverse current	$V_R = 50\text{ V}$	-	-	100	nA
C_d	diode capacitance	$f = 1\text{ MHz}$ (see Figure 2)				
		$V_R = 0\text{ V}$	-	0.30	-	pF
		$V_R = 1\text{ V}$	-	0.22	0.40	pF
		$V_R = 5\text{ V}$	-	0.17	0.30	pF
r_D	diode forward resistance	$f = 100\text{ MHz}$ (see Figure 3)				
		$I_F = 0.5\text{ mA}$	-	4.9	9	Ω
		$I_F = 1\text{ mA}$	-	3.2	6.5	Ω
		$I_F = 10\text{ mA}$	-	1.4	2.5	Ω
		$I_F = 100\text{ mA}$	-	0.9	1.5	Ω
ISL	isolation	$V_R = 0\text{ V}$ (see Figure 5)				
		$f = 900\text{ MHz}$	-	19	-	dB
		$f = 1800\text{ MHz}$	-	15	-	dB
		$f = 2450\text{ MHz}$	-	13	-	dB
L_{ins}	insertion loss	(See Figure 4)				
		$I_F = 0.5\text{ mA}$				
		$f = 900\text{ MHz}$	-	0.36	-	dB
		$f = 1800\text{ MHz}$	-	0.36	-	dB
		$f = 2450\text{ MHz}$	-	0.38	-	dB
		$I_F = 1\text{ mA}$				
		$f = 900\text{ MHz}$	-	0.25	-	dB
		$f = 1800\text{ MHz}$	-	0.26	-	dB
		$f = 2450\text{ MHz}$	-	0.27	-	dB
		$I_F = 10\text{ mA}$				
		$f = 900\text{ MHz}$	-	0.12	-	dB
		$f = 1800\text{ MHz}$	-	0.14	-	dB
		$f = 2450\text{ MHz}$	-	0.15	-	dB
		$I_F = 100\text{ mA}$				
		$f = 900\text{ MHz}$	-	0.09	-	dB
		$f = 1800\text{ MHz}$	-	0.10	-	dB
		$f = 2450\text{ MHz}$	-	0.12	-	dB

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
τ_L	charge carrier life time	when switched from $I_F = 10$ mA to $I_R = 6$ mA; $R_L = 100\ \Omega$; measured at $I_R = 3$ mA	-	0.55	-	μs
L_S	series inductance	$I_F = 100$ mA; $f = 100$ MHz	-	0.4	-	nH

8 Graphical data



9 Package outline



10 Abbreviations

Table 7. Abbreviations

Acronym	Description
PIN	P-type, intrinsic, N-type
SMD	surface-mounted device
RF	radio frequency

11 Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAP51LX v.3	20181126	Product data sheet	-	BAP51LX v.2
Modifications:	• Section 1.2 "Features and benefits" has been updated. • The "Legal information" pages have been updated.			
BAP51LX v.2	20130806	Product data sheet	-	BAP51LX v.1
BAP51LX v.1	20070626	Product data sheet	-	-

12 Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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